

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Islam et al. Date: July 24, 2009
Application No.: 10/561,381 Examiner: F.F.Y. Lopez
Filing Date: December 16, 2005 Group Art Unit: 2826
Title: LEAD FRAME ROUTED CHIP PADS FOR SEMICONDUCTOR PACKAGES

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

*Enter
w/RCE
8/27/09*

AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. § 1.116

Sir:

In response to the final Office Action mailed May 27, 2009, the Examiner is respectfully requested to amend the above-identified application as follows.

Amendments to the claims begin on page 2 of this paper.

Remarks begin on page 5 of this paper.

CERTIFICATE OF MAILING OR TRANSMISSION (37 C.F.R. § 1.8(a))

I hereby certify that this correspondence (along with any paper referred to as being attached or enclosed) is being:

- ☐ deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.
- ☐ transmitted by facsimile on the date shown below to the United States Patent and Trademark Office at (571) 273-8300.
- ☒ transmitted via the electronic filing system of the United States Patent and Trademark Office on the date shown below and in accordance with 37 C.F.R. § 1.6(a)(4).

July 24, 2009

Signed: Brenda Musco

Brenda Musco